



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-10-19
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMG Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LM2904WHYDT	KDO7*0358AEY	A	BO2A	2016-10-19
Amount	UoM	Unit type	ST ECOPACK Grade	
80	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85 - 3.9 - 1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011				
Query				Response
1 - Product(s) meets EU RoHS requirement without any exemptions				true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)				false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)				false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions				false
5 - Product(s) is obsolete, no information is available				false
6 - Product(s) is unknown, no information is available				false
Exemption Id.	Description			
QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KDO7*0358AEY					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	1.027	mg	supplier	die	Silicon (Si)	7440-21-3		1.010	mg	983447	12625
				supplier	metallization	Aluminum (Al)	7429-90-5		0.008	mg	7790	100
				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.004	mg	3895	50
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.005	mg	4869	63
				supplier	alloy	Copper (Cu)	7440-50-8		33.435	mg	967868	417938
Leadframe	Copper & its alloys	34.545	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.786	mg	22753	9825
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.047	mg	1361	588
				supplier	alloy	Zinc (Zn)	7440-66-6		0.041	mg	1187	513
				supplier	metallization	Silver (Ag)	7440-22-4		0.236	mg	6832	2950
				supplier	glue or tape (choose)	Silver (Ag)	7440-22-4		0.385	mg	910165	4813
Die attach	Other inorganic materials	0.423	mg	supplier	glue or tape	acrylate	Proprietary		0.021	mg	49645	263
				supplier	glue or tape	Methacrylate	Proprietary		0.017	mg	40189	213
				supplier	wire	Copper (Cu)	7440-50-8		0.496	mg	1000000	6200
Bonding wire encapsulation	Other inorganic materials	0.496	mg	supplier	wire	Copper (Cu)	7440-50-8		0.496	mg	1000000	6200
				supplier	mold compound	Silica, vitreous	60676-86-0		37.256	mg	877024	465700
	Other Organic Materials	42.480	mg	supplier	mold compound	Epoxy resin A	EC 413-900-7		1.699	mg	39995	21238
				supplier	mold compound	Epoxy resin B	29690-82-2		1.699	mg	39995	21238
				supplier	mold compound	phenol resin	Proprietary		1.274	mg	29991	15925
				supplier	mold compound	carbon black	1333-86-4		0.127	mg	2990	1588
				supplier	mold compound	additive	Proprietary		0.425	mg	10005	5313
connections coating	Solder	1.029	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.029	mg	1000000	12863